

SOT32

plastic single-ended leaded (through hole) package;
mountable to heatsink, 1 mounting hole; 3 leads

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	TO-126
Package type industry code	TO-126
Package style descriptive code	SFM (single-ended flange mount)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	TO-126
Mounting method type	H (heatsink mount)
Issue date	4-3-1997

Table 1. Package summary

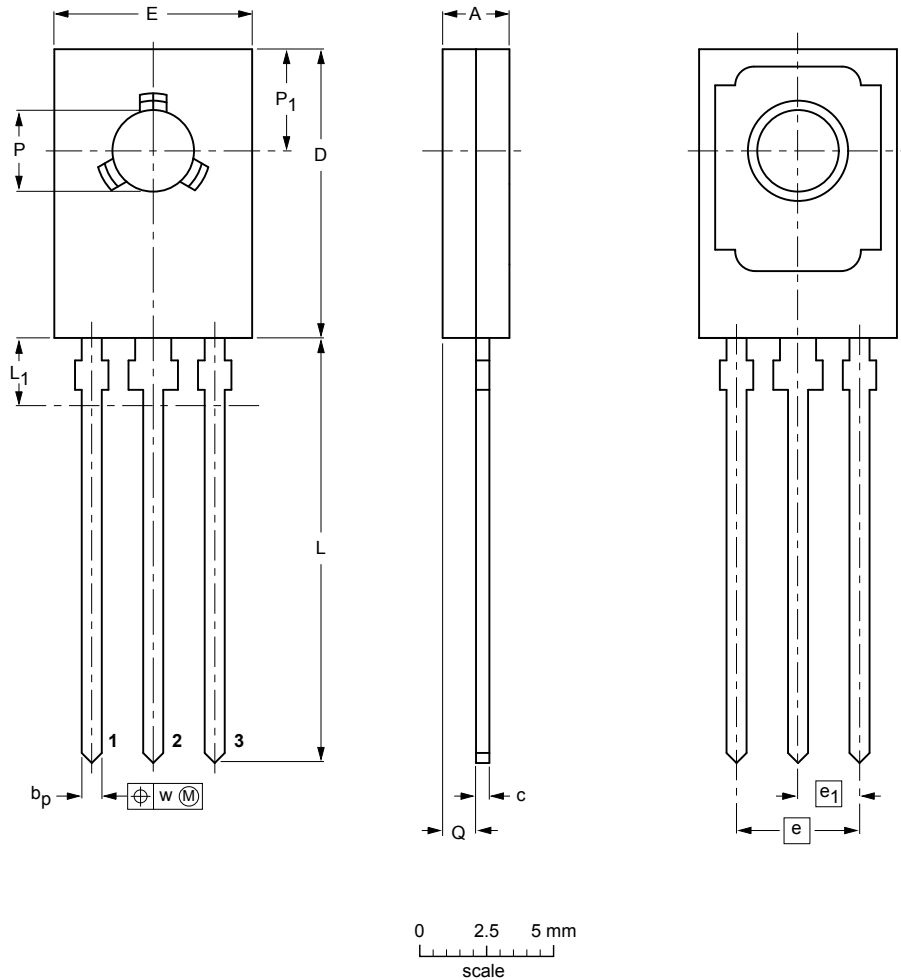
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	10.5	-	10.8	11.1	mm
E	package width	7.2	-	7.5	7.8	mm
A ₂	package height	2.3	-	2.5	2.7	mm
e	nominal pitch	-	-	2.54	-	mm
n ₂	actual quantity of termination	-	-	3	-	



plastic single-ended leaded (through hole) package; mountable to heatsink, 1 mounting hole; 3 leads

2. Package outline

Plastic single-ended leaded (through hole) package; mountable to heatsink, 1 mounting hole; 3 leads SOT32



DIMENSIONS (mm are the original dimensions)

UNIT	A	b_p	c	D	E	e	e_1	L	$L_1^{(1)}$ max	Q	P	P_1	w
mm	2.7 2.3	0.88 0.65	0.60 0.45	11.1 10.5	7.8 7.2	4.58	2.29	16.5 15.3	2.54	1.5 0.9	3.2 3.0	3.9 3.6	0.254

Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ		
SOT32		TO-126			97-03-04

Fig. 1. Package outline TO-126 (SOT32)

plastic single-ended leaded (through hole)
package; mountable to heatsink, 1 mounting
hole; 3 leads

3. Legal information

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

plastic single-ended leaded (through hole)
package; mountable to heatsink, 1 mounting
hole; 3 leads

4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

© NXP Semiconductors N.V. 2016. All rights reserved

For more information, please visit: <http://www.nxp.com>
For sales office addresses, please send an email to: salesaddresses@nxp.com
Date of release: 8 February 2016
